

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:**What Is Claimed is:**

1. (original) A method for disengaging a semiconductor die from a film comprising:
 - forming a plurality of dice on a semiconductor substrate;
 - attaching a bottom surface of the semiconductor substrate to a film
 - dicing the semiconductor substrate into a plurality of individual die, wherein a bottom surface of the plurality of individual die remains attached to the film;
 - disengaging a semiconductor die from the film, wherein disengaging further comprises:
 - placing the plurality of individual die on an anvil;
 - aligning a semiconductor die over an opening in the anvil;
 - projecting a blade through the opening in the anvil to facilitate separation of the semiconductor die from the film, wherein the blade has a surface for disengaging the semiconductor die from the film that is inclined relative to a bottom surface of the semiconductor die; and
 - lifting an edge portion of the semiconductor die above a surface of the anvil with the blade to facilitate disengagement the semiconductor die from the film.
2. (original) The method of claim 1, wherein the semiconductor die is further characterized as gallium arsenide semiconductor die.
3. (original) The method of claim 2, wherein a thickness of the semiconductor die is less than approximately 63.5 microns.
4. (original) The method of claim 3, wherein a thickness of the semiconductor die is less than approximately 25.4 microns.
5. (original) The method of claim 1, wherein the blade extends along more than one axis of the semiconductor die.
6. (original) The method of claim 1, wherein the blade is slotted.
7. (original) The method of claim 1, wherein the blade is oriented diagonally with respect to one of a length and width of the semiconductor die.

8. (original) The method of claim 1, wherein a radius of a surface of the blade contacting the adhesive tape is approximately 127 microns.
9. (original) The method of claim 1, further comprising picking up the semiconductor die after the step of lifting, wherein picking up the semiconductor die includes completely detaching the semiconductor die from the film.
10. (original) The method of claim 1, wherein the film is further characterized as an adhesive tape.

Claims 11-20 (cancelled)